



QPTECHNOLOGIES
MICROELECTRONIC PACKAGING & ASSEMBLY SOLUTIONS

February 2022 Newsletter

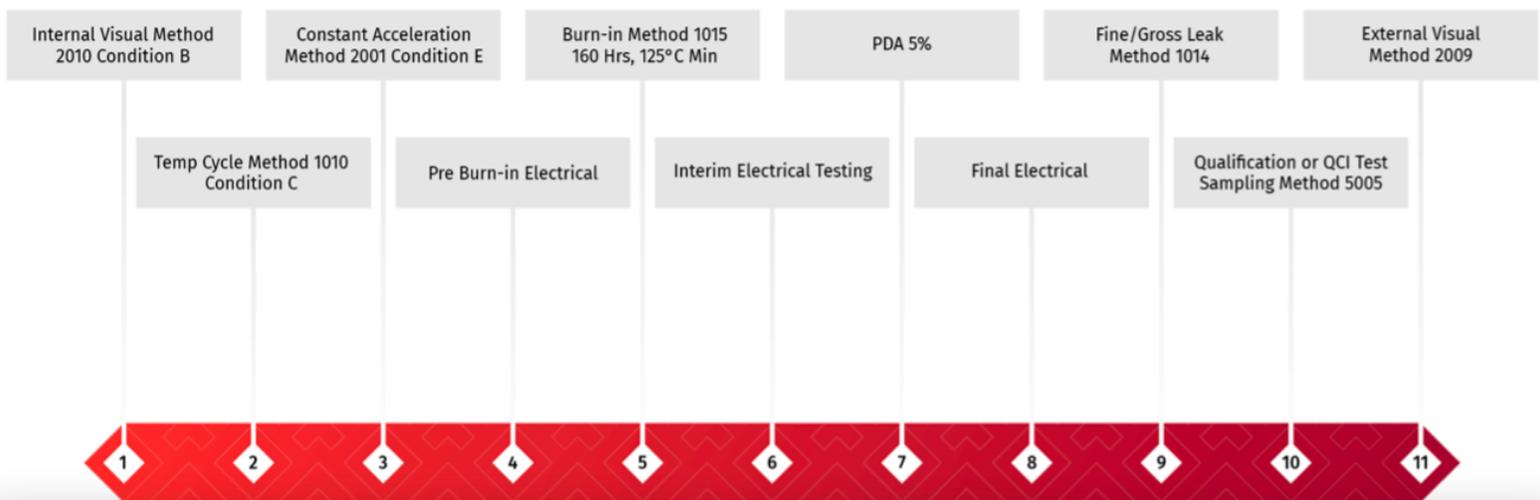
Technology Spotlight: Managing MIL-STD-883 IC Compliance

The military-aerospace market has stringent requirements for parts designed into air, spacecraft, and associated systems. Proven IC and board packaging approaches are essential for enabling system designers to use commercially developed components in military and aerospace applications.

MIL-STD-883 is the military testing standard that determines uniform procedures and methodologies for testing microelectronic devices. It's designed to identify devices suitable for use within military and aerospace electronic systems – i.e., those that can survive harsh natural environments and conditions.

The full standard defines a comprehensive range of processes and procedures. As part of our collaboration with our customers in this market, QP Technologies will assist with the management your circuit qualification per the MIL-STD-883, Method 5004 process flow. Method 5004 falls under Test Procedures – specifically, parts qualification and lot screening. The diagram below illustrates a typical Method 5004 flow that customers utilize to qualify their parts, for both Class B and Class S process steps.

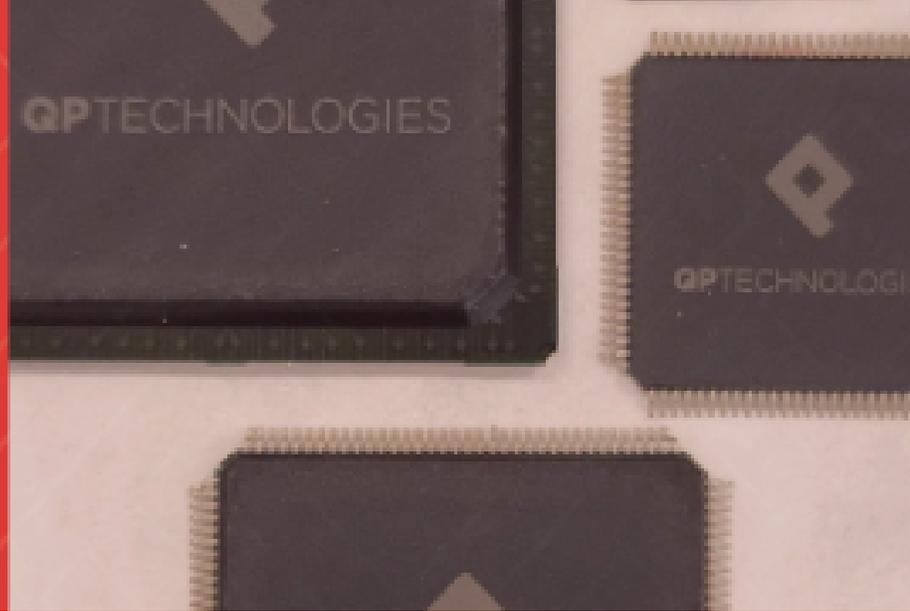
Typical Mil-Std-883, Method 5004 Process Flow



Some devices require full blown qualification flows, and others only require some of these tests be pulled into your flow to ensure a robust device. Ultimately, the purpose of all screens conducted within MIL-STD-883 is to ensure testing, manufacturing, and materials uniformity – in turn, ensuring consistent quality and reliability among all devices screened in accordance with the schedule.

To discuss your mil-aero project scope and requirements with us, [click here](#), or call 858-674-4676.

*News Highlight:
Case Study in Aerospace
& Defense Technology*



The February issue of Aerospace & Defense Technology features a case study that showcases one of our key offerings for the mil-aero market. Jointly authored by QP Technologies senior packaging engineer Sam Sadri and Tom Tammen, CEO of avionics ASIC provider Device Engineering, Inc., the article shares the process by which the two companies collaborated to create a solution using our open-cavity plastic packaging (OCP) technology. Customers in the mil-aero space are increasingly turning to OCP as a cost-effective means of creating a new package that fits an established footprint while providing the high robustness and MSL rating required.

To read the full article, click [here](#). To hear Sam share more about this project and our OCP offering, please plan sure to attend our poster session at GOMACTech 2022 (further details below).



Employee Spotlight:

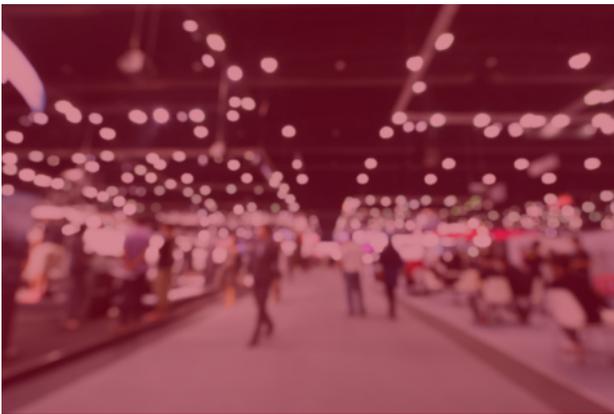
Dustie Rivera, Senior Customer Service Representative

Keeping our customers happy is a top priority, and our stellar customer service team is focused on doing just that. This month, we're shining our spotlight on senior customer service rep Dustie Rivera. In her role, she works with sales and other departments to ensure jobs are released and to promote continuous improvement throughout QP Technologies.



Dustie came on board with us last April after relocating to the San Diego area, along with her kids, her dogs and her cat. Previously, she had spent more than 20 years with Integra Technologies in Wichita, Kansas, where she held a succession of positions managing production, materials, configuration and customer service.

Dustie is highly focused on team building, believing companies that do well and continue to be successful are those that know how to be the best at building strong, well-functioning teams. This spirit is a key aspect of what makes Dustie such a valuable member of our team.



Upcoming Shows:

iMAPS DPC and GOMACTech

As we move further into 2022, it's exciting to see in-person trade shows and conferences coming back. QP Technologies is participating in two important events next month – starting with the 18th iMAPS International Conference and Exhibition on Device Packaging (DPC), March 7-10, in Fountain Hills,

Arizona. In addition to exhibiting in booth 61, we are a silver-level sponsor for this year's event, which will feature several exciting keynotes on the future of packaging, advanced packaging techniques, and sustainability considerations.

Later in the month, you can find us at GOMACTech 2022 in Miami, Florida, March 21-24. In our booth 710, attendees can learn about our mil-aero-optimize packaging and assembly capabilities and how we collaborate with customers to help manage their MIL-STD-883 project flow. During the Poster Session on Wed., March 23, our senior packaging engineer Sam Sadri will give a presentation titled "Open-Cavity Plastic Packages (OCP): A Robust IC Solution for High-Reliability Mil-Aero Applications," expanding on the work covered in the article jointly authored by QP Technologies and Device Engineering, Inc. (DEI) that appears in the February issue Aerospace & Defense Technology. Whether in AZ or FL, we look forward to seeing you soon!

About QP Technologies

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.

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